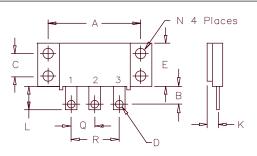
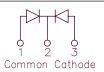
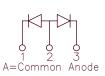
Schottky Powermod FST160100











Baseplate: Nickel plated copper;

electrically isolated Pins: Nickel plated copper

Microsemi	Working Peak
Catalog Number	Reverse Voltage

Repetitive Peak Reverse Voltage

FST16090* FST160100*

90V 100V

90V 100V

*Add the Suffix A for Common Anode, D for Doubler

Dim.	Inches	Millimeters		
Min.	Max.	Min.	Max.	Notes
A 1.995	2.005	50.67	50.93	
B 0.300	0.325	7.62	8.26	
C 0.495	0.505	12.57	12.83	
D 0.182	0.192	4.62	4.88	Dia.
E 0.990	1.010	25.15	25.65	
F 2.390	2.410	60.71	61.21	
G 1.500	1.525	38.10	38.70	
H 0.120	0.130	3.05	3.30	
J	0.400		10.16	
K 0.240	0.260	6.10	6.60 to	Lead G
L 0.490	0.510	12.45	12.95	_
M 0.330	0.350	8.38	6.90	
N 0.175	0.195	4.45	4.95	Dia.
P 0.035	0.045	0.89	1.14	
Q 0.445	0.455	11.30	11.56	
R 0.890	0.910	22.61	23.11	

T0 - 249

- Schottky Barrier Rectifier
- Guard Ring for Reverse Protection
- VRRM 90 to 100 Volts
- High Surge Capacity
- Reverse Energy Tested
- ROHS Compliant

Electrical Characteristics

F(AV) 160 Amps

Average forward current per pkg Average forward current per leg Maximum surge current per leg Max repetitive peak reverse current per $leg_{R}(OV)$ 2 Amps Max peak forward voltage per leg Max peak forward voltage per leg Max peak reverse current per leg

Max peak reverse current per leg

Typical junction capacitance per leg

F(AV) 80 Amps İFSM 1200 Amps VFM .75 Volts VFМ .96 Volts RМ 30 mA RM 2 mA Çj 1500 pF

^TC = 120°C, Square wave, R θJC = 0.5°C/W $^{T}C = 120^{\circ}C$, Square wave, $R \Theta JC = 0.9^{\circ}C/W$ 8.3 ms, half sine $T_J = 175^{\circ}C$ f = 1 KHz, 25°C, 1µsec Square wave $T_J = 175^{\circ}C^{\circ}$

IFM = 80A: TJ = 25°C* VRRM, TJ = 125°C* VRRM, TJ = 25°C $VR = 5.0V, TJ = 25^{\circ}C$

*Pulse test: Pulse width 300 µsec, Duty cycle 2%

Thermal and Mechanical Characteristics

Storage temp range Operating junction temp range Maximum thermal resistance per lea Max thermal resistance per pkg. Typical thermal resistance (greased) Mounting torque Weight

TSTG ТJ $\mathsf{R} \ominus \mathsf{JC}$ $\mathsf{R} \; \theta \mathsf{JC}$ Recs

-55°C to 175°C -55°C to 175°C 0.9°C/W Junction to case 0.5°C/W Junction to case 0.1°C/W Case to sink 15 - 20 inch pounds 2.5 ounces (71 grams) typical



FST16090 - FST160100

Figure 1
Typical Forward Characteristics

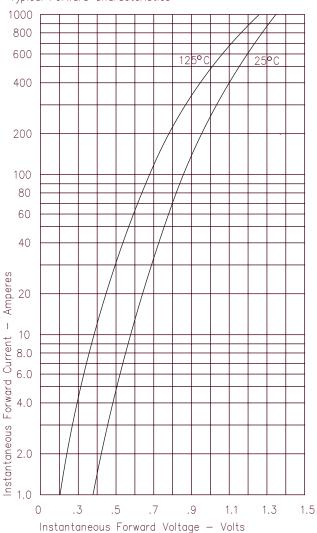


Figure 2 Typical Reverse Characteristics

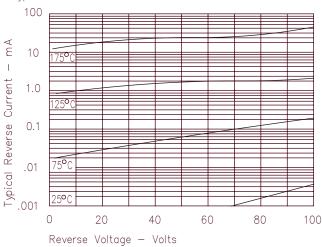


Figure 3 Typical Junction Capacitance

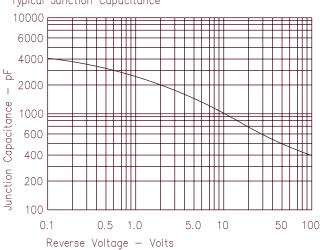


Figure 4
Forward Current Derating

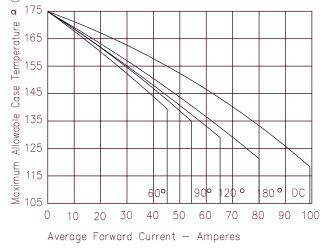


Figure 5 Maximum Forward Power Dissipation



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